

L Number	Hits	Search Text	DB	Time stamp
1	28	(US-5866933-\$ or US-5278105-\$ or US-5475251-\$ or US-4672221-\$ or US-5369299-\$ or US-5468990-\$ or US-5050123-\$ or US-5061978-\$ or US-5488251-\$ or US-5821582-\$ or US-6326675-\$ or US-6072328-\$ or US-6198155-\$ or US-5907008-\$ or US-5717224-\$ or US-5702849-\$ or US-5622787-\$ or US-6281266-\$ or US-6163062-\$ or US-6259495-\$ or US-5990491-\$ or US-RE37591-\$ or US-6380561-\$ or US-5966193-\$ or US-6031593-\$).did. or (US-20010003374-\$).did. or (JP-61296738-\$ or JP-11038221-\$).did.	USPAT; US-PGPUB; JPO	2004/11/03 18:05
2	1	"2002024148"	USPAT; US-PGPUB; JPO	2004/11/03 18:05
3	1	"6413847"	USPAT; US-PGPUB; JPO	2004/11/03 18:05
4	4	"6207479"	USPAT; US-PGPUB; JPO	2004/11/03 18:05
5	19	"5930663"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:06
6	18	"5336624"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:07
7	0	jp0361147551a	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:08
8	1	jp361147551a	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:13
9	8	"5345105"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
10	5	"5861652"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
11	10	"4434361"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
12	7	"6137318"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
13	5	"6014052"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
14	8	"5998858"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:12
15	1	jp410270562a	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:18
16	2	"5873846"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:18
17	27	"5866933"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:19
18	11	"5973375"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:19
19	13	"6117762"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:19

20	90	"2002024148" "6413847" "6207479" "5930663" "5336624" jp361147551a "5345105" "5861652" "4434361" "6137318" "6014052" "5998858" jp410270562a "5873846" "5866933" "5973375" "6117762"	USPAT; US-PGPUB; EPO; JPO	2004/11/03 18:20
-	826	reverse nearl engineering) (opaque nearl conductive nearl shielding	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 08:16
-	826	reverse nearl engineering) (opaque nearl conductive nearl shielding	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:52
-	46	(reverse nearl engineering) (opaque nearl conductive nearl shielding) and (semiconductor adj device)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 08:56
-	0	20010041431.URPN.	USPAT	2002/07/08 08:20
-	12	("4268911" "4603381" "4766516" "4843026" "4885617" "5010032" "5187122" "5465005" "5661085" "5804470" "5821150" "5834356").PN.	USPAT	2002/07/08 08:24
-	0	6326675.URPN.	USPAT	2002/07/08 08:27
-	4	5866933.URPN.	USPAT	2002/07/08 08:32
-	42	("3946426" "4139864" "4164461" "4267578" "4291391" "4314268" "4471376" "4581628" "4583011" "4603381" "4623255" "4727493" "4766516" "4799096" "4821085" "4975756" "5030796" "5050123" "5061978" "5065208" "5068697" "5070378" "5101121" "5117276" "5132571" "5138197" "5146117" "5202591" "5227649" "5231299" "5302539" "5308682" "5309015" "5336624" "5354704" "5369299" "5376577" "5399441" "5441902" "5468990" "5475251" "5539224").PN.	USPAT	2002/07/08 08:33
-	307	(reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:18
-	261	((reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))) not ((reverse nearl engineering) (opaque nearl conductive nearl shielding) and (semiconductor adj device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 08:58
-	0	((reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))) not ((reverse nearl engineering) (opaque nearl conductive nearl shielding) and (semiconductor adj device))) and (blocking near (film layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 08:59
-	4	((reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))) not ((reverse nearl engineering) (opaque nearl conductive nearl shielding) and (semiconductor adj device))) and (aluminum adj oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 09:00

-	57	((reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))) not ((reverse nearl engineering) (opaque nearl conductive nearl shielding) and (semiconductor adj device))) and blocking	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 09:00
-	0	6326675.URPN.	USPAT	2002/07/08 09:42
-	0	6198155.URPN.	USPAT	2002/07/08 09:42
-	7	("4243427" "4849296" "5203915" "5221558" "5399441" "5591680" "5744244").PN.	USPAT	2002/07/08 09:44
-	0	6198155.URPN.	USPAT	2002/07/08 09:44
-	9	5468990.URPN.	USPAT	2002/07/08 09:45
-	2	5821582.URPN.	USPAT	2002/07/08 09:48
-	9	("4030952" "5030796" "5070386" "5109267" "5231299" "5308682" "5337274" "5369299" "5468990").PN.	USPAT	2002/07/08 09:48
-	7	("4030952" "5030796" "5070386" "5109267" "5231299" "5308682" "5337274").PN.	USPAT	2002/07/08 09:50
-	9	5468990.URPN.	USPAT	2002/07/08 09:51
-	2	("4030952" "5109267").PN.	USPAT	2002/07/08 09:51
-	16	5369299.URPN.	USPAT	2002/07/08 09:51
-	9	5061978.URPN.	USPAT	2002/07/08 10:21
-	5	("4291326" "4419533" "4621275" "4654536" "4672221").PN.	USPAT	2002/07/08 10:23
-	13	5475251.URPN.	USPAT	2002/07/08 10:25
-	35	5278105.URPN.	USPAT	2002/07/08 10:27
-	7	("4711701" "4916514" "4949162" "4963501" "4973562" "5032890" "5132237").PN.	USPAT	2002/07/08 10:31
-	17	4672221.URPN.	USPAT	2002/07/08 10:32
-	832	reverse nearl engineering) (opaque nearl conductive nearl shielding	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:17
-	307	(reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:53
-	1	((reverse nearl engineering) (opaque nearl conductive nearl shielding) and ((semiconductor adj (chip device)) (integrated adj circuit))) and (light near (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:55
-	13	(US-6326675-\$ or US-6198155-\$ or US-5866933-\$ or US-5475251-\$ or US-5278105-\$ or US-5468990-\$ or US-5369299-\$ or US-5061978-\$ or US-5050123-\$ or US-5821582-\$ or US-4672221-\$ or US-5488251-\$).did. or (US-20010003374-\$).did.	USPAT; US-PGPUB	2002/07/08 13:20
-	2	(reverse nearl engineering) (opaque nearl conductive nearl shielding) and (light near (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:20

-	46749	(light near (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:16
-	2	((light near (blocking shielded shielding shield))) and (reverse near engineering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:23
-	2	((light near (blocking shielded shielding shield))) and (reverse near1 engineering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:33
-	39713	(light adj (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:29
-	10	((light adj (blocking shielded shielding shield))) near3 (corrosion adj resistance)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:30
-	40	((light adj (blocking shielded shielding shield))) with (aluminum adj oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/08 13:37
-	2	5702849.URPN.	USPAT	2002/07/08 13:58
-	8	("3740280" "4722878" "4981771" "5049461" "5115465" "5154949" "5181132" "5233211").PN.	USPAT	2002/07/08 13:59
-	9	5061978.URPN.	USPAT	2002/07/08 14:06
-	138	(silicon adj nitride) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 08:55
-	5	((silicon adj nitride) near3 corrosion) and ((passivation plasma) near1 nitride)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 08:55
-	2	((passivation plasma) near1 nitride) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:04
-	0	((passivation plasma) near nitride) near3 (silicon adj nitride) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:03
-	0	((passivation plasma) near nitride) near3 (silicon adj nitride)) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:03
-	0	((passivation plasma) near1 nitride) near3 (silicon adj nitride)) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:03
-	2	((passivation plasma) near nitride) near3 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:04
-	3	((passivation plasma) near nitride) near4 corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:05
-	9	((passivation plasma) near nitride) with corrosion	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:05
-	6	((passivation plasma) near nitride) with corrosion) not ((passivation plasma) near nitride) near4 corrosion)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:06

-	585	((light adj (blocking shielded shielding shield))) and (aluminum adj oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:16
-	39738	(light adj (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:16
-	1078	(passivation plasma protective) near4 (aluminum adj oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:18
-	1912	(passivation plasma protective cover covering covered) near4 (aluminum adj oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:18
-	15	((light adj (blocking shielded shielding shield))) and ((passivation plasma protective) near4 (aluminum adj oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:19
-	31	((light adj (blocking shielded shielding shield))) and ((passivation plasma protective cover covering covered) near4 (aluminum adj oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 09:19
-	0	(light adj blocking adj film) near6 (principal adj part)	US-PGPUB	2002/07/09 10:43
-	17	((light adj (blocking shielded shielding shield))) near3 (tantalum niobium)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/09 10:44
-	903	reverse near1 engineering) (opaque near1 conductive near1 shielding	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:53
-	348	(reverse near1 engineering) (opaque near1 conductive near1 shielding) and ((semiconductor near1 (chip package device)) (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:54
-	1	((reverse near1 engineering) (opaque near1 conductive near1 shielding) and ((semiconductor near1 (chip package device)) (integrated adj circuit))) and (light near1 (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:56
-	6	((reverse near1 engineering) (opaque near1 conductive near1 shielding) and ((semiconductor near1 (chip package device)) (integrated adj circuit))) and (light with (blocking shielded shielding shield))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/25 15:56